PRELIMINARY

W212

Frequency Timing Generator for ALI 1641

Features

- **Maximized EMI Suppression using Cypress's Spread Spectrum technology**
- **I²C™ interface**
- **Two copies of CPU Output**
- **One copy of IOAPIC Output**
- **Six copies of PCI Output**
- **Two copies of AGP Output**
- **One copy of selectable 48-MHz or 24-MHz Output**
- **Thirteen copies of SDRAM Output**
- **Two buffered copy of 14.318-MHz reference clock**
- **Mode input pin selects optional power management input control pins (reconfigures pins 19, 20, 21 and 22)**
- **Smooth frequency transition upon frequency reselection**
- **Available in 48-pin SSOP (300 mils)**

Key Specifications

Supply Voltages: ..... V_{DDQ3} = 3.3V±5%
V_{DDQ2} = 2.5V±5%

CPU Cycle to Cycle Jitter: ..... 250 ps

CPU Outputs Skew: ..... 175 ps

CPU to AGP Offset: ..... <500 ps

CPU to SDRAM Offset: ..... <500 ps

CPU to PCI Offset: ..... 1.0 to 3.0 ns (CPU leads)

AGP Outputs Skew: ..... 250 ps

SDRAM Outputs Skew: ..... 250 ps

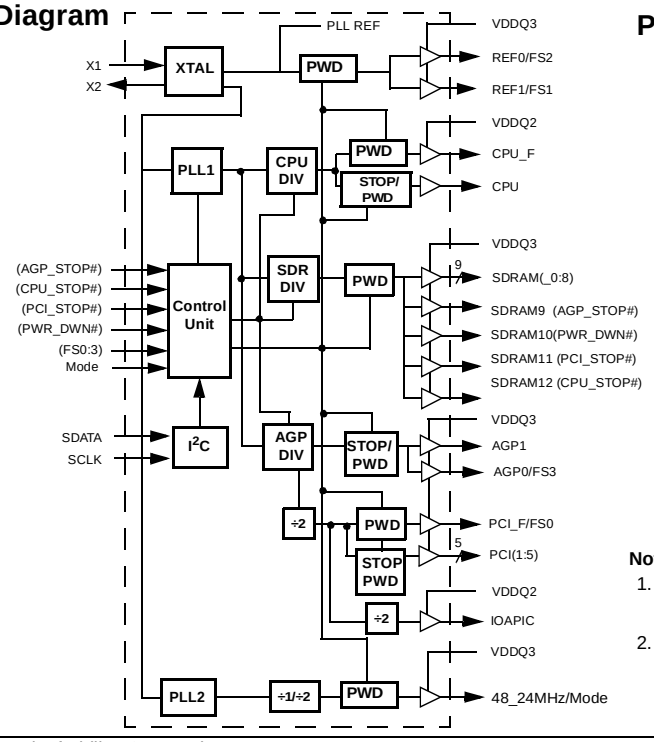
PCI Outputs Skew: ..... 500 ps

AGP to PCI Skew: ..... TBD

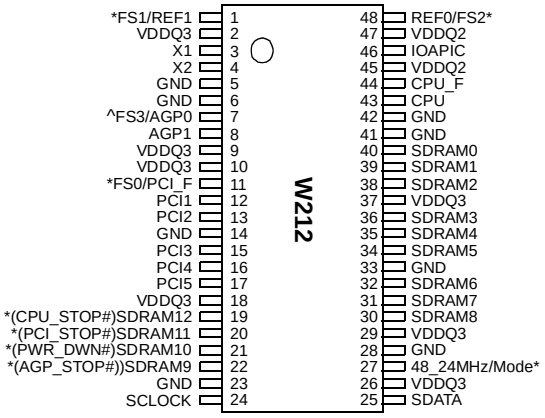
Table 1. Pin Selectable Frequency (Center Spread)

Input Address				CPU (MHz)	SDRAM (MHz)	AGP (MHz)	PCI (MHz)	APIC (MHz)
FS3	FS2	FS1	FS0					
0	0	0	0	66.8	100.2	66.8	33.4	16.7
0	0	0	1	100.2	100.2	66.8	33.4	16.7
0	0	1	0	66.8	66.8	66.8	33.4	16.7
0	0	1	1	133.6	100.2	66.8	33.4	16.7
0	1	0	0	66.8	133.6	66.8	33.4	16.7
0	1	0	1	100.2	133.6	66.8	33.4	16.7
0	1	1	0	100.2	66.8	66.8	33.4	16.7
0	1	1	1	133.6	133.6	66.6	33.4	16.7
1	0	0	0	95.0	95.0	63.3	31.6	15.8
1	0	0	1	95.0	126.6	63.3	31.6	15.8
1	0	1	0	105.0	140.0	70.0	35.0	17.5
1	0	1	1	110.0	110.0	73.3	36.6	18.3
1	1	0	0	122.0	122.0	61.0	30.5	15.3
1	1	0	1	122.0	91.5	61.0	30.5	15.3
1	1	1	0	140.0	105.0	70.0	35.0	17.5
1	1	1	1	146.0	146.0	73.0	36.5	18.3

Block Diagram



Pin Configuration[1]



Note:

1. Signal names with (*) denotes pins have internal 140K pull-up resistor, though not relied upon for pulling to V_{DDQ3}. Signal names with parentheses denotes function is selectable by MODE pin strapping.
2. Signal names with (^) denotes pins have internal 55K pull-down resistor, though not relied upon for pulling to V_{DDQ3}. Signal names with parentheses denotes function is selectable by MODE pin strapping.

I²C is a trademark of Philips Corporation.

Pin Definitions

Pin Name	Pin No.	Pin Type	Pin Description
CPU_F	44	O	***Free Running CPU Clock:*** This clock output is not affected by the CPU_STOP# control pin. Output voltage swing is controlled by voltage applied to VDDQ2.
CPU	43	O	***CPU Clock Output:*** This output is controlled by the CPU_STOP# control pin. Output voltage swing is controlled by voltage applied to VDDQ2.
PCI_F/FS0	11	I/O	***Free-running PCI Clock Output and Frequency Selection Bit 0:*** As an output, this pin works in conjunction with PCI1:5. Output voltage swing is controlled by voltage applied to VDDQ3. When an input, this pin functions as part of the frequency selection address. The value of FS0:3 determines the power-up default frequency of device output clocks as per *Table 1* on page 1.
PCI1:5	12, 13, 15, 16, 17	O	***PCI Clock Outputs 1 through 5:*** Output voltage swing is controlled by voltage applied to VDDQ3. Outputs are held LOW if PCI_STOP# is set LOW.
SDRAM0:8	30, 31,32, 34, 35, 36,38, 39, 40	O	***SDRAM Clock Outputs:*** These nine SDRAM clock outputs run synchronous to the CPU clock outputs or AGP clock output.
SDRAM9/ AGP_STOP#	22	I/O	***SDRAM Clock Output and AGP Stop:*** The SDRAM clock outputs run synchronous to the CPU clock outputs or AGP clock output. If programmed as inputs (refer to MODE pin description), this pin is used for AGP stop control. When input is LOW, pin will be at logic zero.
SDRAM10/ PWR_DWN#	21	I/O	***SDRAM Clock Output and Power Down:*** The SDRAM clock outputs run synchronous to the CPU clock outputs or AGP clock output. If programmed as inputs (refer to MODE pin description), this pin is used for power-down control. The asynchronous active LOW input pin disables the internal clocks with the VCO and crystal stopped.
SDRAM11/ PCI_STOP#	20	I/O	***SDRAM Clock Output and PCI Stop:*** The SDRAM clock outputs run synchronous to the CPU clock outputs or AGP clock output. If programmed as inputs (refer to MODE pin description), this pin is used for PCI stop control. All PCI pins except for PCI_F will be at logic zero.
SDRAM12/ CPU_STOP#	19	I/O	***SDRAM Clock Output and CPU Stop:*** The SDRAM clock outputs run synchronous to the CPU clock outputs or AGP clock output. If programmed as inputs (refer to MODE pin description), this pin is used to stop all CPU clocks except for the CPU_F clock. When input is LOW, pin will be at logic zero.
48_24MHz/ MODE	27	I/O	***48-MHz or 24-MHz Output, and MODE Control:*** Selectable clock output that defaults to 48 MHz following device power-up. When an input, this pin functions as a select pin for either Desktop Mode (1) or Mobile Mode (0).
REF0/FS2	48	I/O	***Reference Clock Output and Frequency Select Input:*** 14.318-MHz Reference Clock. When configured as an input, this pin is a frequency select pin.
REF1/FS1	1	I/O	***Reference Clock Output and Frequency Select Input:*** 14.318-MHz Reference Clock. When configured as an input, this pin is a frequency select pin.
AGP0/FS3, AGP1	7, 8	O	***AGP Output:*** This output is controlled by the AGP_STOP# pin.
IOAPIC	46	O	***I/O APIC Clock Output:*** The output voltage swing is set by the power connection to VDDQ2.
X1	3	I	***Crystal Connection or External Reference Frequency Input:*** This pin has dual functions. It can be used as an external 14.318-MHz crystal connection or as an external reference frequency input.
X2	4	I	***Crystal Connection:*** An input connection for an external 14.318-MHz crystal. If using an external reference, this pin must be left unconnected.
SDATA	25	I	***Serial Data Input:*** Data input for Serial Data Interface. Refer to Serial Data Interface section that follows.
SCLOCK	24	I	***Serial Clock Input:*** Clock input for Serial Data Interface. Refer to Serial Data Interface section that follows.

Pin Definitions (continued)

Pin Name	Pin No.	Pin Type	Pin Description
VDDQ3	2, 9, 10, 18, 26, 29, 37	P	***Power Connection:*** Connected to 3.3V supply.
VDDQ2	45, 47	P	***Power Connection:*** Connected to 2.5V supply.
GND	5, 6, 14, 23, 28, 33, 41, 42	G	***Ground Connection:*** Connect all ground pins to the common system ground plane.

W212 Pin Selection Tables

Table 2. Mode Function

Pin Function				
MODE	**Pin 19**	**Pin 20**	**Pin 21**	**Pin 22**
1	SDRAM12	SDRAM11	SDRAM10	SDRAM9
0	CPU_STOP#	PCI_STOP#	PWR_DWN#	AGP_STOP#

Table 3. Power Management Pin Function

Signal	= 0	= 1
CPU_STOP#	CPU = LOW	Active
PCI_STOP#	PCI1:5 = LOW	Active
AGP_STOP#	AGP0:1 = LOW	Active
PWR_DWN#	All Clock Outputs LOW	Active

Overview

The W212 was designed specifically to provide all clock signals required for a motherboard designed with the ALI 1641 PII/PIII style chipset.

Thirteen SDRAM outputs are provided for support of up to 3 SDRAM DIMM modules. Unused clock outputs can be disabled through the I^2C interface to reduce system power consumption and more importantly reduce EMI emissions.

Functional Description

I/O Pin Operation

Pins 1, 7, 11, 19, 20, 21, 22, 27, and 48 are dual-purpose I/O pins. Upon power-up these pins act as logic inputs, allowing the determination of assigned device functions. A short time after power-up, the logic state of each pin is latched and the pins then become clock outputs. This feature reduces device pin count by combining clock outputs with input select pins.

An external 10-kΩ “strapping” resistor is connected between each I/O pin and ground or V_{DDQ3}. Connection to ground sets a latch to “0,” connection to V_{DDQ3} sets a latch to “1.” *Figure 1* and *Figure 2* show two suggested methods for strapping resistor connection.

Upon W212 power-up, the first 2 ms of operation is used for input logic selection. During this period, the 48_24MHz, REF1, PCI_F, AGP0 and SDRAM9:12 clock output buffers are three-stated, allowing the output strapping resistor on each I/O pin to pull the pin and its associated capacitive clock load to either a logic HIGH or logic LOW state. At the end of the 2-ms period, the established logic 0 or 1 condition of each I/O is pin is latched. Next the output buffers are enabled, converting all I/O pins into operating clock outputs. The 2-ms timer starts when V_{DDQ3} reaches 2.0V. The input bits can only be reset by turning V_{DDQ3} off and then back on again.

It should be noted that the strapping resistors have no significant effect on clock output signal integrity. The drive impedance of the clock output is 40Ω (nominal) which is minimally affected by the 10-kΩ strap to ground or V_{DDQ3}. As with the series termination resistor, the output strapping resistor should be placed as close to the I/O pin as possible in order to keep the interconnecting trace short. The trace from the resistor to ground or V_{DDQ3} should be kept less than two inches in length to prevent system noise coupling during input logic sampling.

When the clock outputs are enabled following the 2-ms input period, target (normal) output frequency is delivered, assuming that V_{DDQ3} has stabilized. If V_{DDQ3} has not yet reached full value, output frequency initially may be below target but will increase to target once V_{DDQ3} voltage has stabilized. In either case, a short output clock cycle may be produced from the CPU clock outputs when the outputs are enabled.

CPU/ SDRAM/ AGP/ PCI Frequency Selection

CPU output frequency is selected with I/O pins 1, 7, 11, and 48. Refer to *Table 2* for CPU/PCI frequency programming information. Alternatively, frequency selections are available through the serial data interface. Refer to *Table 7*, “Additional Frequency Selections through Serial Data Interface Data Bytes (Down Spread),” on page 8.

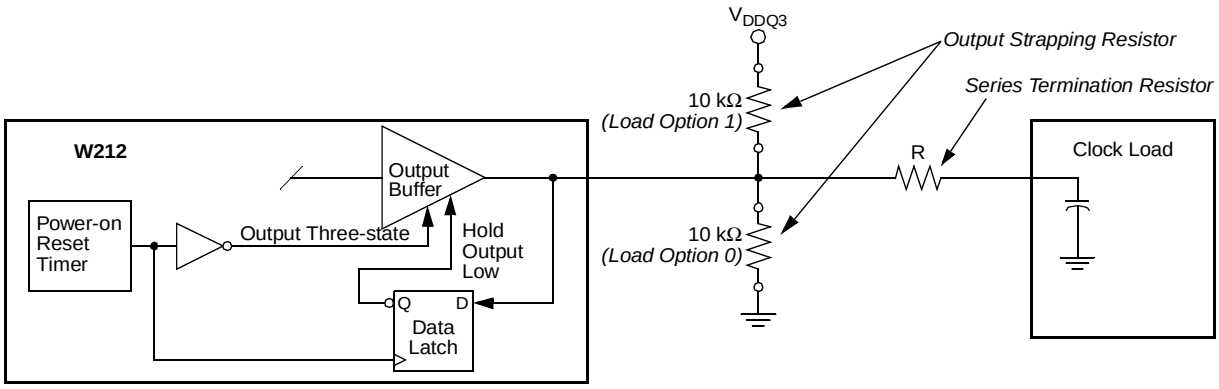


Figure 1. Input Logic Selection Through Resistor Load Option

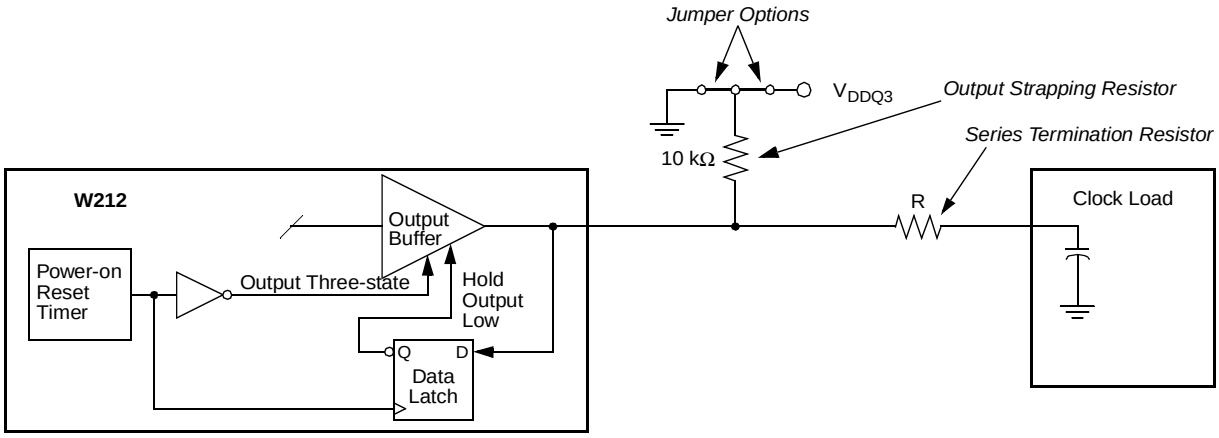


Figure 2. Input Logic Selection Through Jumper Option

Output Buffer Configuration

Clock Outputs

All clock outputs are designed to drive serially terminated clock lines. The W212 outputs are CMOS-type which provide rail-to-rail output swing.

Crystal Oscillator

The W212 requires one input reference clock to synthesize all output frequencies. The reference clock can be either an externally generated clock signal or the clock generated by the internal crystal oscillator. When using an external clock signal, pin X1 is used as the clock input and pin X2 is left open. The input threshold voltage of pin X1 is (V_{DDQ3})/2.

The internal crystal oscillator is used in conjunction with a quartz crystal connected to device pins X1 and X2. This forms a parallel resonant crystal oscillator circuit. The W212 incorporates the necessary feedback resistor and crystal load capacitors. Including typical stray circuit capacitance, the total load presented to the crystal is approximately 20 pF. For optimum frequency accuracy without the addition of external capacitors, a parallel-resonant mode crystal specifying a load of 20 pF should be used. This will typically yield reference frequency accuracies within ±100 ppm. To achieve similar accuracies with a crystal calling for a greater load, external capacitors must be added such that the total load (internal, external, and parasitic capacitors) equals that called for by the crystal.

Serial Data Interface

The W212 features a two-pin, serial data interface that can be used to configure internal register settings that control particular device functions. Upon power-up, the W212 initializes with default register settings, therefore the use of this serial data interface is optional. The serial interface is write-only (to the clock chip) and is the dedicated function of device pins SDATA and SCLOCK. In motherboard applications, SDATA and SCLOCK are typically driven by two logic outputs of the chipset. Clock device register changes are normally made upon system initialization, if any are required. The interface can also be used during system operation for power management functions. *Table 4* summarizes the control functions of the serial data interface.

Operation

Data is written to the W212 in ten bytes of eight bits each. Bytes are written in the order shown in *Table 5*.

Table 4. Serial Data Interface Control Functions Summary

Control Function	Description	Common Application
Clock Output Disable	Any individual clock output(s) can be disabled. Disabled outputs are actively held LOW.	Unused outputs are disabled to reduce EMI and system power. Examples are clock outputs to unused SDRAM DIMM socket or PCI slot.
CPU Clock Frequency Selection	Provides CPU/PCI frequency selections through software. Frequency is changed in a smooth and controlled fashion.	For alternate CPU devices, and power management options. Smooth frequency transition allows CPU frequency change under normal system operation.
Output Three-state	Puts clock output into a high-impedance state.	Production PCB testing.
(Reserved)	Reserved function for future device revision or production device testing.	No user application. Register bit must be written as 0.

Table 5. Byte Writing Sequence

Byte Sequence	Byte Name	Bit Sequence	Byte Description
1	Slave Address	11010010	Commands the W212 to accept the bits in Data Bytes 0–6 for internal register configuration. Since other devices may exist on the same common serial data bus, it is necessary to have a specific slave address for each potential receiver. The slave receiver address for the W212 is 11010010. Register setting will not be made if the Slave Address is not correct (or is for an alternate slave receiver).
2	Command Code	Don't Care	Unused by the W212, therefore bit values are ignored ("Don't Care"). This byte must be included in the data write sequence to maintain proper byte allocation. The Command Code Byte is part of the standard serial communication protocol and may be used when writing to another addressed slave receiver on the serial data bus.
3	Byte Count	Don't Care	Unused by the W212, therefore bit values are ignored ("Don't Care"). This byte must be included in the data write sequence to maintain proper byte allocation. The Byte Count Byte is part of the standard serial communication protocol and may be used when writing to another addressed slave receiver on the serial data bus.
4	Data Byte 0	Refer to *Table 6*	The data bits in Data Bytes 0–7 set internal W212 registers that control device operation. The data bits are only accepted when the Address Byte bit sequence is 11010010, as noted above. For description of bit control functions, refer to *Table 6*, Data Byte Serial Configuration Map.
5	Data Byte 1		
6	Data Byte 2		
7	Data Byte 3		
8	Data Byte 4		
9	Data Byte 5		
10	Data Byte 6		

Writing Data Bytes

Each bit in the data bytes controls a particular device function except for the “reserved” bits which must be written as a logic 0. Bits are written MSB (most significant bit) first, which is bit 7. *Table 6* gives the bit formats for registers located in Data Bytes 0–6.

Table 7 details additional frequency selections that are available through the serial data interface.

Table 6. Data Bytes 0–6 Serial Configuration Map

Bit(s)	Affected Pin		Control Function	Bit Control		Default
	Pin No.	Pin Name		0	1	
Data Byte 0						
7	--	--	SEL_3	Refer to *Table 7*		0
6	--	--	SEL_2			0
5	--	--	SEL_1			0
4	--	--	SEL_0			0
3	11, 1, 48, 7	FS0:3	BYT0 /FS#	Frequency Controlled by external pins FS 0:2	Frequency Controlled by SEL _0:3, above	0
2-1	--	--	Bit 2 Bit 1 Function 0 0 ±0.5% Center Spread 0 1 –0.5% Down Spread 1 0 (Reserved) 1 1 All Outputs Three-stated			00
0	27	48_24#MHz	1 = 48 MHz 0 = 24 MHz			1
Data Byte 1						
7	27	48_24#MHz	Clock Output Disable	Low	Active	1
6	--	--	(Reserved)	--	--	1
5	--	--	(Reserved)	--	--	1
4	--	--	(Reserved)	--	--	1
3	--	--	(Reserved)	--	--	1
2	--	--	(Reserved)	--	--	1
1	43	CPU	Clock Output Disable	Low	Active	1
0	44	CPU_F	Clock Output Disable	Low	Active	1
Data Byte 2						
7	11	PCI_F	Clock Output Disable	Low	Active	1
6	--	--	(Reserved)	--	--	1
5	17	PCI5	Clock Output Disable	Low	Active	1
4	16	PCI4	Clock Output Disable	Low	Active	1
3	15	PCI3	Clock Output Disable	Low	Active	1
2	13	PCI2	Clock Output Disable	Low	Active	1
1	12	PCI1	Clock Output Disable	Low	Active	1
0	--		Clock Output Disable	Low	Active	1
Data Byte 3						
7	31	SDRAM7	Clock Output Disable	Low	Active	1
6	32	SDRAM6	Clock Output Disable	Low	Active	1
5	34	SDRAM5	Clock Output Disable	Low	Active	1
4	35	SDRAM4	Clock Output Disable	Low	Active	1
3	36	SDRAM3	Clock Output Disable	Low	Active	1
2	38	SDRAM2	Clock Output Disable	Low	Active	1

Table 6. Data Bytes 0–6 Serial Configuration Map (continued)

Bit(s)	Affected Pin		Control Function	Bit Control		Default
	Pin No.	Pin Name		0	1	
1	39	SDRAM1	Clock Output Disable	Low	Active	1
0	40	SDRAM0	Clock Output Disable	Low	Active	1
Data Byte 4						
7	--	--	(Reserved)	--	--	0
6	--	--	(Reserved)	--	--	1
5		--	(Reserved)	--	--	1
4	19	SDRAM12	Clock Output Disable	Low	Active	1
3	20	SDRAM11	Clock Output Disable	Low	Active	1
2	21	SDRAM10	Clock Output Disable	Low	Active	1
1	22	SDRAM9	Clock Output Disable	Low	Active	1
0	30	SDRAM8	Clock Output Disable	Low	Active	1
Data Byte 5						
7	--		(Reserved)	--	--	0
5	--		(Reserved)	--	--	0
5	--		(Reserved)	--	--	0
4	48	REF0	Clock Output Disable	Low	Active	1
3	1	REF1	Clock Output Disable	Low	Active	1
2	7	AGP0	Clock Output Disable	Low	Active	1
1	8	AGP1	Clock Output Disable	Low	Active	1
0	46	IOAPIC	Clock Output Disable	Low	Active	1
Data Byte 6						
7	--	--	(Reserved)	--	--	0
6	--	--	(Reserved)	--	--	0
5	--	--	(Reserved)	--	--	0
4	--	--	(Reserved)	--	--	0
3	--	--	(Reserved)	--	--	0
2	--	--	(Reserved)	--	--	1
1	--	--	(Reserved)	--	--	1
0	--	--	(Reserved)	--	--	0
7	--	--	SEL_3	Refer to *Table 7*		0

Table 7. Additional Frequency Selections through Serial Data Interface Data Bytes (Down Spread)

Input Conditions				Output Frequency				
Data Byte 0				CPU Clocks (MHz)	SDRAM (MHz)	AGP (MHz)	PCI Clocks (MHz)	APCI Clocks (MHz)
Bit 7	Bit 6	Bit 5	Bit 4					
0	0	0	0	66.6	100.0	66.6	33.3	16.7
0	0	0	1	100.0	100.0	66.6	33.3	16.7
0	0	1	0	66.6	66.6	66.6	33.3	16.7
0	0	1	1	133.3	100.0	66.6	33.3	16.7
0	1	0	0	66.6	133.3	66.6	33.3	16.7
0	1	0	1	100.0	133.3	66.6	33.3	16.7
0	1	1	0	100.0	66.6	66.6	33.3	16.7
0	1	1	1	133.3	133.3	66.6	33.3	16.7
1	0	0	0	95.0	95.0	63.3	31.6	15.8
1	0	0	1	95.0	126.6	63.3	31.6	15.8
1	0	1	0	105.0	140.0	70.0	35.0	17.5
1	0	1	1	110.0	110.0	73.3	36.6	18.3
1	1	0	0	122.0	122.0	61.0	30.5	15.3
1	1	0	1	122.0	91.5	61.0	30.5	15.3
1	1	1	0	140.0	105.0	70.0	35.0	17.5
1	1	1	1	146.0	146.0	73.0	36.5	18.3

Absolute Maximum Ratings

Stresses greater than those listed in this table may cause permanent damage to the device. These represent a stress rating only. Operation of the device at these or any other conditions above those specified in the operating sections of this specification is not implied. Maximum conditions for extended periods may affect reliability.

Parameter	Description	Rating	Unit
V_{DDQ3}, V_{IN}	Voltage on any pin with respect to GND	–0.5 to +7.0	V
T_{STG}	Storage Temperature	–65 to +150	°C
T_B	Ambient Temperature under Bias	–55 to +125	°C
T_A	Operating Temperature	0 to +70	°C
ESD_{PROT}	Input ESD Protection	2 (min.)	kV

3.3V DC Electrical Characteristics: T_A = 0°C to +70°C, V_{DDQ3} = 3.3V±5%, V_{DDQ2} = 2.5V±5%

Parameter	Description		Test Condition	Min.	Typ.	Max.	Unit
Supply Current							
I_{DD}	3.3V Supply Current		CPU, CPU_F=133.3 MHz Outputs Loaded[3]		TBD		mA
I_{DD}	2.5V Supply Current		CPU, CPU_F=133.3 MHz Outputs Loaded[3]		TBD		mA
Logic Inputs							
V_{IL}	Input Low Voltage					0.8	V
V_{IH}	Input High Voltage			2.0			V
I_{IL}	Input Low Current[4]					20	µA
I_{IH}	Input High Current[4]					5	µA
Clock Outputs							
V_{OL}	Output Low Voltage		I_{OL} = 1 mA			50	mV
V_{OH}	Output High Voltage		I_{OH} = –1 mA	3.1			V
V_{OH}	Output High Voltage	CPU,CPU_F	I_{OH} = –1 mA	2.2			V
I_{OL}	Output Low Current	CPU; CPU_F	V_{OL} = 1.5V	55	75	105	mA
		SDRAM0:12, AGP0:1		80	110	155	mA
		PCI_F, PCI1:5		55	75	105	mA
		REF0:1		60	75	90	mA
		48/24 MHZ		55	75	105	mA
I_{OH}	Output High Current	CPU; CPU_F	V_{OH} = 1.5V	55	85	125	mA
		SDRAM0:12, AGP0:1		80	120	175	mA
		PCI_F, PCI1:5		55	85	125	mA
		REF0:1		60	85	110	mA
		48/24 MHZ		55	85	125	mA

Notes:

3. All clock outputs loaded with maximum lump capacitance test load specified in AC Electrical Characteristics section.
4. W212 logic inputs have internal pull-up devices (not full CMOS level).

3.3V DC Electrical Characteristics: T_A = 0°C to +70°C, V_{DDQ3} = 3.3V±5%, V_{DDQ2} = 2.5V±5% (continued)

Parameter	Description	Test Condition	Min.	Typ.	Max.	Unit
Crystal Oscillator						
V_{TH}	X1 Input Threshold Voltage[5]	V_{DDQ3} = 3.3V		1.65		V
C_{LOAD}	Load Capacitance, Imposed on External Crystal[6]			20		pF
$C_{IN,X1}$	X1 Input Capacitance[7]	Pin X2 unconnected		30		pF
Pin Capacitance/Inductance						
C_{IN}	Input Pin Capacitance	Except X1 and X2			5	pF
C_{OUT}	Output Pin Capacitance				6	pF
L_{IN}	Input Pin Inductance				7	nH
Serial Input Port						
V_{IL}	Input Low Voltage	V_{DDQ3} = 3.3V			$0.3V_{DDQ3}$	V
V_{IH}	Input High Voltage	V_{DDQ3} = 3.3V	$0.7V_{DDQ3}$			V
I_{IL}	Input Low Current				10	µA
I_{IH}	Input High Current				10	µA
I_{OL}	Sink Current into SDATA or SCLOCK, Open Drain N-Channel Device On	$I_{OL} = 0.3(V_{DDQ3})$	6			mA
C_{IN}	Input Capacitance of SDATA and SCLOCK				10	pF
C_{SDATA}	Total Capacitance of SDATA Bus				400	pF
C_{SCLOCK}	Total Capacitance of SCLOCK Bus				400	pF

AC Electrical Characteristics

T_A = 0°C to +70°C, V_{DDQ3} = 3.3V±5%,V_{DDQ2} = 2.5V± 5% f_{XTL} = 14.31818 MHz

AC clock parameters are tested and guaranteed over stated operating conditions using the stated lump capacitive load at the clock output.

AGP Clock Outputs, AGP0:1 (Lump Capacitance Test Load = 20 pF)

Parameter	Description	Test Condition/Comments	CPU = 66.6 MHz			Unit
			Min.	Typ.	Max.	
t_P	Period	Measured on rising edge at 1.5V	15			ns
f	Frequency, Actual	Determined by PLL divider ratio		TBD		MHz
t_H	High Time	Duration of clock cycle above 2.4V	5.2			ns
t_L	Low Time	Duration of clock cycle below 0.4V	5			ns
t_R	Output Rise Edge Rate	Measured from 0.4V to 2.4V	1		4	V/ns
t_F	Output Fall Edge Rate	Measured from 2.4V to 0.4V	1		4	V/ns
t_D	Duty Cycle	Measured on rising and falling edge at 1.5V	45		55	%
t_{JC}	Jitter, Cycle-to-Cycle	Measured on rising edge at 1.5V. Maximum difference of cycle time between two adjacent cycles.			250	ps
t_{SK}	Output Skew	Measured on rising edge at 1.5V			175	ps
f_{ST}	Frequency Stabilization from Power-up (cold start)	Assumes full supply voltage reached within 1 ms from power-up. Short cycles exist prior to frequency stabilization.			3	ms
Z_o	AC Output Impedance	Average value during switching transition. Used for determining series termination value.	15	20	30	Ω

Notes:

5. X1 input threshold voltage (typical) is $V_{DDQ3}/2$.
6. The W212 contains an internal crystal load capacitor between pin X1 and ground and another between pin X2 and ground. Total load placed on crystal is 20 pF; this includes typical stray capacitance of short PCB traces to crystal.
7. X1 input capacitance is applicable when driving X1 with an external clock source (X2 is left unconnected).

CPU Clock Outputs, CPU0:1 (Lump Capacitance Test Load = 20 pF)

Parameter	Description	Test Condition/ Comments	CPU = 66.6 MHz			CPU = 100 MHz			CPU = 133 MHz			Unit
			Min.	Typ.	Max.	Min.	Typ.	Max.	Min.	Typ.	Max.	
t_P	Period	Measured on rising edge at 1.5V	15			10			7.5			ns
f	Frequency, Actual	Determined by PLL divider ratio		TBD			TBD			TBD		MHz
t_H	High Time	Duration of clock cycle above 2.4V	5.2			3.0			1.87			ns
t_L	Low Time	Duration of clock cycle below 0.4V	5			2.8			1.67			ns
t_R	Output Rise Edge Rate	Measured from 0.4V to 2.4V	1		4	1		4	1		4	V/ns
t_F	Output Fall Edge Rate	Measured from 2.4V to 0.4V	1		4	1		4	1		4	V/ns
t_D	Duty Cycle	Measured on rising and falling edge at 1.5V	45		55	45		55	45		55	%
t_{JC}	Jitter, Cycle-to-Cycle	Measured on rising edge at 1.5V. Maximum difference of cycle time between two adjacent cycles.			250			250			250	ps
t_{SK}	Output Skew	Measured on rising edge at 1.5V			175			175			175	ps
f_{ST}	Frequency Stabilization from Power-up (cold start)	Assumes full supply voltage reached within 1 ms from power-up. Short cycles exist prior to frequency stabilization.			3			3			3	ms
Z_o	AC Output Impedance	Average value during switching transition. Used for determining series termination value.	15	20	30	15	20	30	15	20	30	Ω

SDRAM Clock Outputs, SDRAM0:12 (Lump Capacitance Test Load = 30 pF)

Parameter	Description	Test Condition/ Comments	SDRAM = 66.6 MHz			SDRAM = 100 MHz			SDRAM = 133 MHz			Unit
			Min.	Typ.	Max.	Min.	Typ.	Max.	Min.	Typ.	Max.	
t_P	Period	Measured on rising edge at 1.5V	15			10			7.5			ns
f	Frequency, Actual	Determined by PLL divider ratio	TBD			TBD			TBD			MHz
t_R	Output Rise Edge Rate	Measured from 0.4V to 2.4V	1		4	1		4	1		4	V/ns
t_F	Output Fall Edge Rate	Measured from 2.4V to 0.4V	1		4	1		4	1		4	V/ns
t_D	Duty Cycle	Measured on rising and falling edge at 1.5V	45		55	45		55	45		55	%
t_{JC}	Jitter, Cycle-to-Cycle	Measured on rising edge at 1.5V. Maximum difference of cycle time between two adjacent cycles.			250			250			250	ps
t_{SK}	Output Skew	Measured on rising edge at 1.5V		100			100			100		ps
t_{SK}	CPU to SDRAM Clock Skew	Covers all CPU/SDRAM outputs. Measured on rising edge at 1.5V.			500			500			500	ps
f_{ST}	Frequency Stabilization from Power-up (cold start)	Assumes full supply voltage reached within 1 ms from power-up. Short cycles exist prior to frequency stabilization.			3			3			3	ms
Z_o	AC Output Impedance	Average value during switching transition. Used for determining series termination value.	10	15	20	10	15	20	10	15	20	Ω

PCI Clock Outputs, PCI0:5 (Lump Capacitance Test Load = 30 pF

Parameter	Description	Test Condition/Comments	PCI = 33.3 MHz			Unit
			Min.	Typ.	Max.	
t_P	Period	Measured on rising edge at 1.5V	30			ns
f	Frequency, Actual	Determined by PLL divider ratio		TBD		MHz
t_H	High Time	Duration of clock cycle above 2.4V	12			ns
t_L	Low Time	Duration of clock cycle below 0.4V	12			ns
t_R	Output Rise Edge Rate	Measured from 0.4V to 2.4V	1		4	V/ns
t_F	Output Fall Edge Rate	Measured from 2.4V to 0.4V	1		4	V/ns
t_D	Duty Cycle	Measured on rising and falling edge at 1.5V	45		55	%
t_{JC}	Jitter, Cycle-to-Cycle	Measured on rising edge at 1.5V. Maximum difference of cycle time between two adjacent cycles.			250	ps
t_{SK}	Output Skew	Measured on rising edge at 1.5V			250	ps
t_O	CPU to PCI Clock Skew	Covers all CPU/PCI outputs. Measured on rising edge at 1.5V. CPU leads PCI output.	1		3	ns
f_{ST}	Frequency Stabilization from Power-up (cold start)	Assumes full supply voltage reached within 1 ms from power-up. Short cycles exist prior to frequency stabilization.			3	ms
Z_o	AC Output Impedance	Average value during switching transition. Used for determining series termination value.		20		Ω

REF Clock Output (Lump Capacitance Test Load = 45 pF)

Parameter	Description	Test Condition/Comments	Min.	Typ.	Max.	Unit
f	Frequency, Actual	Frequency generated by crystal oscillator		14.31818		MHz
t_R	Output Rise Edge Rate	Measured from 0.4V to 2.4V	0.5		2	V/ns
t_F	Output Fall Edge Rate	Measured from 2.4V to 0.4V	0.5		2	V/ns
t_D	Duty Cycle	Measured on rising and falling edge at 1.5V	40		60	%
f_{ST}	Frequency Stabilization from Power-up (cold start)	Assumes full supply voltage reached within 1 ms from power-up. Short cycles exist prior to frequency stabilization.			1.5	ms
Z_o	AC Output Impedance	Average value during switching transition. Used for determining series termination value.		30		Ω

48-/24-MHz Clock Output (Lump Capacitance Test Load = 20 pF)

Parameter	Description	Test Condition/Comments	Min.	Typ.	Max.	Unit
f	Frequency, Actual	Determined by PLL divider ratio (see m/n below)		48.008/24.004		MHz
f_D	Deviation from 48 MHz	(48.008 – 48)/48		+167		ppm
m/n	PLL Ratio	(14.31818 MHz x 57/17 = 48.008 MHz)		57/17, 54/34		
t_R	Output Rise Edge Rate	Measured from 0.4V to 2.4V	0.5		2	V/ns
t_F	Output Fall Edge Rate	Measured from 2.4V to 0.4V	0.5		2	V/ns
t_D	Duty Cycle	Measured on rising and falling edge at 1.5V	45		55	%
f_{ST}	Frequency Stabilization from Power-up (cold start)	Assumes full supply voltage reached within 1 ms from power-up. Short cycles exist prior to frequency stabilization.			3	ms
Z_o	AC Output Impedance	Average value during switching transition. Used for determining series termination value.		30		Ω

24-MHz Clock Output (Lump Capacitance Test Load = 20 pF)

Parameter	Description	Test Condition/Comments	Min.	Typ.	Max.	Unit
f_{SCLOCK}	SCLOCK Frequency	Normal Mode	0		100	kHz
t_{STHD}	Start Hold Time		4.0			µs
t_{LOW}	SCLOCK Low Time		4.7			µs
t_{HIGH}	SCLOCK High Time		4.0			µs
t_{DSU}	Data Set-up Time		250			ns
t_{DHD}	Data Hold Time	(Transmitter should provide a 300-ns hold time to ensure proper timing at the receiver.)	0			ns
t_R	Rise Time, SDATA and SCLOCK	From $0.3V_{DDQ3}$ to $0.7V_{DDQ3}$			1000	ns
t_F	Fall Time, SDATA and SCLOCK	From $0.7V_{DDQ3}$ to $0.3V_{DDQ3}$			300	ns
t_{STSU}	Stop Setup Time		4.0			µs
t_{SPF}	Bus Free Time between Stop and Start Condition		4.7			µs
t_{SP}	Allowable Noise Spike Pulse Width				50	ns

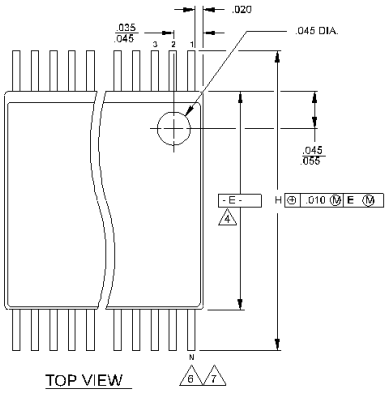
Ordering Information

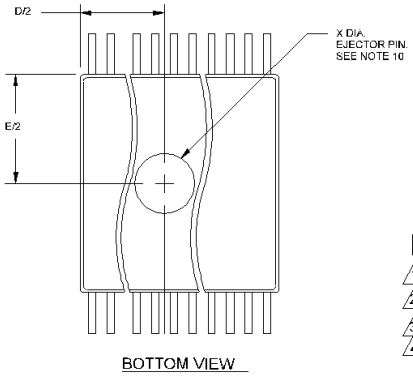
Ordering Code	Package Name	Package Type
W212	H	48-pin SSOP (300 mils)

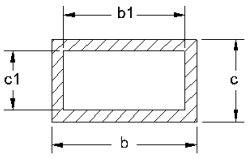
Document #: 38-00915-**

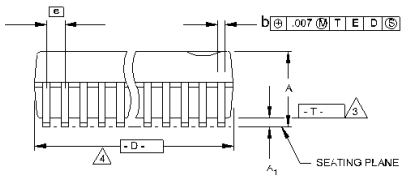
Package Diagram

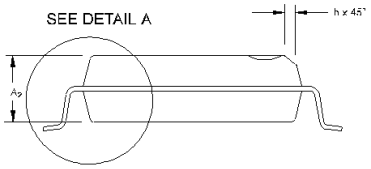
48-Pin Small Shrink Outline Package (SSOP, 300 mils)

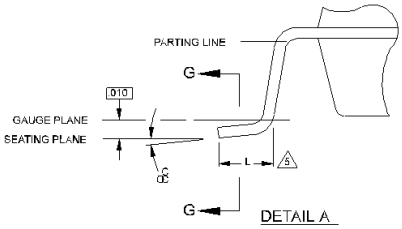












NOTES:

1. MAXIMUM DIE THICKNESS ALLOWABLE IS .025.
2. DIMENSIONING & TOLERANCING PER ANSI Y14.5M - 1982.
3. "T" IS A REFERENCE DATUM.
4. "D" & "E" ARE REFERENCE DATUMS AND DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS, BUT DOES INCLUDE MOLD MISMATCH AND ARE MEASURED AT THE MOLD PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED .006 INCHES PER SIDE.
5. "L" IS THE LENGTH OF TERMINAL FOR SOLDERING TO A SUBSTRATE.
6. "N" IS THE NUMBER OF TERMINAL POSITIONS.
7. TERMINAL POSITIONS ARE SHOWN FOR REFERENCE ONLY.
8. FORMED LEADS SHALL BE PLANAR WITH RESPECT TO ONE ANOTHER WITHIN .003 INCHES AT SEATING PLANE.
9. CONTROLLING DIMENSION: INCHES.
10. COUNTRY OF ORIGIN LOCATION AND EJECTOR PIN ON PACKAGE BOTTOM IS OPTIONAL AND DEPENDS ON ASSEMBLY LOCATION.
11. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .005 INCHES AND .010 INCHES FROM THE LEAD TIPS.
12. THIS PART IS COMPLIANT WITH JEDEC SPECIFICATION MO-118, VARIATIONS AA, AB, EXCEPT CHAMFER DIMENSION h. JEDEC SPECIFICATION FOR h IS .015"/.025".

SYMBOL	COMMON DIMENSIONS				NOTE	4			6
	MIN.	NOM.	MAX.	b_{01}	VARI-ATIONS	D MIN.	D NOM.	D MAX.	N
A	.095	.102	.110		AA	.620	.625	.630	48
A_1	.008	.012	.016		AB	.720	.725	.730	56
A_2	.088	.090	.092						
b	.008	.010	.0135						
b_1	.008	.010	.012						
c	.005	-	.010						
c_1	.005	.006	.0085						
D	SEE VARIATIONS			4					
E	.292	.296	.299						
e	.025 BSC								
H	.400	.406	.410						
h	.010	.013	.016						
L	.024	.032	.040						
N	SEE VARIATIONS			6					
X	.085	.093	.100	10					
α	0°	5°	8°						

THIS TABLE IN INCHES

Summary of nominal dimensions in inches:

Body Width: 0.296
Lead Pitch: 0.025
Body Length: 0.625
Body Height: 0.102

SYMBOL	COMMON DIMENSIONS				NOTE	4			6
	MIN.	NOM.	MAX.	b_{01}	VARI-ATIONS	D MIN.	D NOM.	D MAX.	N
A	2.41	2.59	2.79		AA	15.75	15.88	16.00	48
A_1	0.20	0.31	0.41		AB	18.29	18.42	18.54	56
A_2	2.24	2.29	2.34						
b	0.203	0.254	0.343						
b_1	0.203	0.254	0.305						
c	0.127	-	0.254						
c_1	0.127	0.152	0.216						
D	SEE VARIATIONS			4					
E	7.42	7.52	7.59						
e	0.635 BSC								
H	10.16	10.31	10.41						
h	0.25	0.33	0.41						
L	0.61	0.81	1.02						
N	SEE VARIATIONS			6					
X	2.16	2.36	2.54	10					
α	0°	5°	8°						

THIS TABLE IN MILLIMETERS